

Title (en)

METHOD FOR PRODUCING HEAT BONDED PACKAGES AND TOOL FOR IMPLEMENTING SAID METHOD

Title (de)

VERFAHREN ZUR HERSTELLUNG VON HEISSIEGEL-VERPACKUNGEN UND EIN WERKZEUG ZUR DURCHFÜHRUNG DES VERFAHRENS

Title (fr)

PROCEDE DE FABRICATION D'EMBALLAGES THERMOSOUEDES ET OUTIL PERMETTANT DE METTRE EN OEUVRE LEDIT PROCEDE

Publication

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Application

EP 99939445 A 19990802

Priority

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- EP 9905608 W 19990802

Abstract (en)

[origin: DE19837763A1] Two layers of multilayer material are placed with their plastic layers in contact and the temperature of the sealing tools (1,2) is reduced to just above the melting point of the plastic layer to lower the temperature in the packaging material (3,4). Welding time is increased, preferably doubled, while the total cycle time remains the same. An Independent claim is made for a sealing tool for the process which has two or more welding faces (9) corresponding to the weld lines behind each other in the feed direction, the spacing of the welding faces in the feed direction equaling the feed distance per cycle.

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IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 0010795A1

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